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FCA35N60 N-Channel SuperFET[®] MOSFET

600 V, 35 A, 98 m Ω

Features

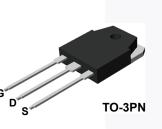
- 650V @ T_J = 150°C
- Typ. R_{DS(on)} = 79 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 139 nC)
- Low Effective Output Capacitance (Typ. $C_{oss(eff.)} = 340 \text{ pF}$)
- 100% Avalanche Tested

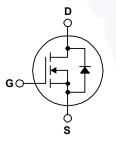
Applications

- Solar Inverter
- AC-DC Power Supply

Description

SuperFET[®] MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		FCA35N60	Unit			
V _{DSS}	Drain to Source Voltage		600	V		
V _{GSS}	Gate-Soure voltage			±30	V	
I _D	DrainCurrent	- Continuous (T _C = 25°C)		35	Α	
		- Continuous (T _C = 100 ^o C)		22.2		
I _{DM}	Drain Current	- Pulsed	(Note 1)	105	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)			1455	mJ	
I _{AR}	Avalanche Current		(Note 1)	35	Α	
E _{AR}	Repetitive Avalanche Ene	rgy	(Note 1)	31.25	mJ	
dv/dt	Peak Diode Recovery dv/c	(Note 3)	20	V/ns		
P _D	Dewer Dissinction	$(T_{\rm C} = 25^{\rm o}{\rm C})$		312.5	W	
	Power Dissipation	- Derate Above 25°C		2.5	W/ºC	
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C	

Thermal Characteristics

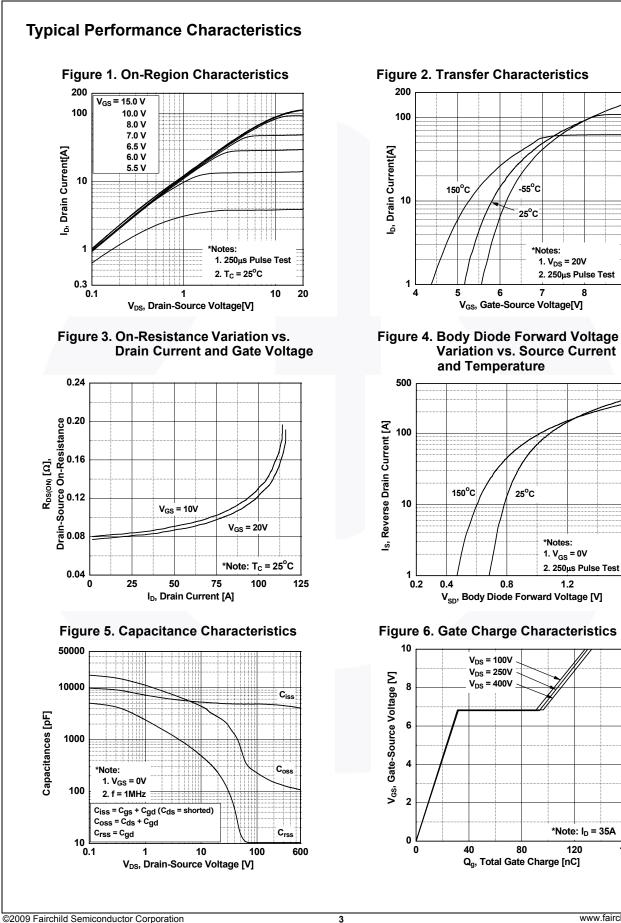
Symbol	Parameter	FCA35N60	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.4	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient, Max.	42	0/10

May 2014

		Top Mark	Package	Packing Method	Reel Size	Tape Width		Qua	Quantity	
		TO-3PN	Tube	N/A	N/A		30 units			
Electrical	Chara		5 ⁰ C unless c	otherwise noted						
Symbol		Parameter		Test Conditio	ons	Min.	Тур.	Max.	Unit	
Off Charac	teristics									
	Drain to Source Breakdown Voltage		~~ I	$\begin{split} I_D &= 250 \; \mu\text{A}, \text{V}_{\text{GS}} = 0 \; \text{V}, \text{T}_{\text{J}} = 25^{\text{o}}\text{C} \\ \hline I_D &= 250 \; \mu\text{A}, \text{V}_{\text{GS}} = 0 \; \text{V}, \text{T}_{\text{J}} = 150^{\text{o}}\text{C} \\ \hline I_D &= 250 \; \mu\text{A}, \text{Referenced to } 25^{\text{o}}\text{C} \end{split}$		600	-	-	V	
BV _{DSS}			l I			-	650	-	V	
ΔBV_{DSS} / ΔT_{J}			I			-	0.6	-	V/°C	
BV _{DS}	Drain-Source Avalanche Breakdown Voltage		wn	V _{GS} = 0 V, I _D = 16 A		-	700	-	V	
1	Zoro Cat	Voltago Drain Current		V _{DS} = 600 V, V _{GS} = 0 V		-	-	1		
I _{DSS}	Zero Gale	e Voltage Drain Current	N N	V _{DS} = 480 V, T _C = 125 ^o C		-	-	10	μA	
I _{GSS}	Gate to Body Leakage Current			$V_{\rm GS}$ = ±30 V, $V_{\rm DS}$ = 0 V		-	-	±100	nA	
On Charact	teristics									
V _{GS(th)}	Gate Thr	eshold Voltage	ľ	V _{GS} = V _{DS} , I _D = 250 μA		3.0	-	5.0	V	
R _{DS(on)}	Static Dra	atic Drain to Source On Resistance $V_{GS} = 10 \text{ V}, I_D = 17.5 \text{ A}$			-	0.079	0.098	Ω		
9 _{FS}	Forward Transconductance		1	V _{DS} = 40 V, I _D = 17.5 A			28.8	-	S	
Dynamic C	haracter	istics								
C _{iss}	Input Cap			V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		-	4990	6640	pF	
C _{oss}		apacitance				-	2380	3170	pF	
C _{rss}		Transfer Capacitance	1			-	140	-	pF	
C _{oss}	Output Capacitance			V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz		-	113	-	pF	
C _{oss(eff.)}	Effective	Output Capacitance		$V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$		-	340	-	pF	
Qg	Total Gate	e Charge at 10V		V _{DS} = 480 V, I _D = 35 A,		-	139	181	nC	
Q _{gs}	Gate to S	ource Gate Charge		$V_{\rm GS} = 460$ V, $I_{\rm D} = 35$ A, V _{GS} = 10 V (Note 4)		-	31	-	nC	
Q _{gd}		rain "Miller" Charge				-	69	-	nC	
ESR	Equivalent Series Resistance (G-S)		S) 1	f = 1 MHz			1.4	-	Ω	
Switching	Characte	eristics					1			
	1	Delay Time				-	34	78	ns	
t _{d(on)} t _r		Rise Time	,	V _{DD} = 300 V, I _D = 35 A,	-		120	250	ns	
		Delay Time		$V_{GS} = 10 \text{ V}, \text{ R}_{G} = 4.7 \Omega$			105	220	ns	
t _{d(off)} t _f	Turn-Off F						73	155	ns	
	1				(Note 4)	-	75	155	113	
		e Characteristics								
I _S	Maximum Continuous Drain to Source Dio					-	-	35	A	
I _{SM}	Maximum Pulsed Drain to Source Diode F					-	-	105	A	
V _{SD}		Source Diode Forward Vo		V _{GS} = 0 V, I _{SD} = 35 A		-	-	1.4	V	
t _{rr}		Recovery Time		V _{GS} = 0 V, I _{SD} = 35 A, dI _F /dt = 100 A/µs		-	614	-	ns	
Q _{rr}	Reverse F	Recovery Charge	0			-	16.3	-	μC	

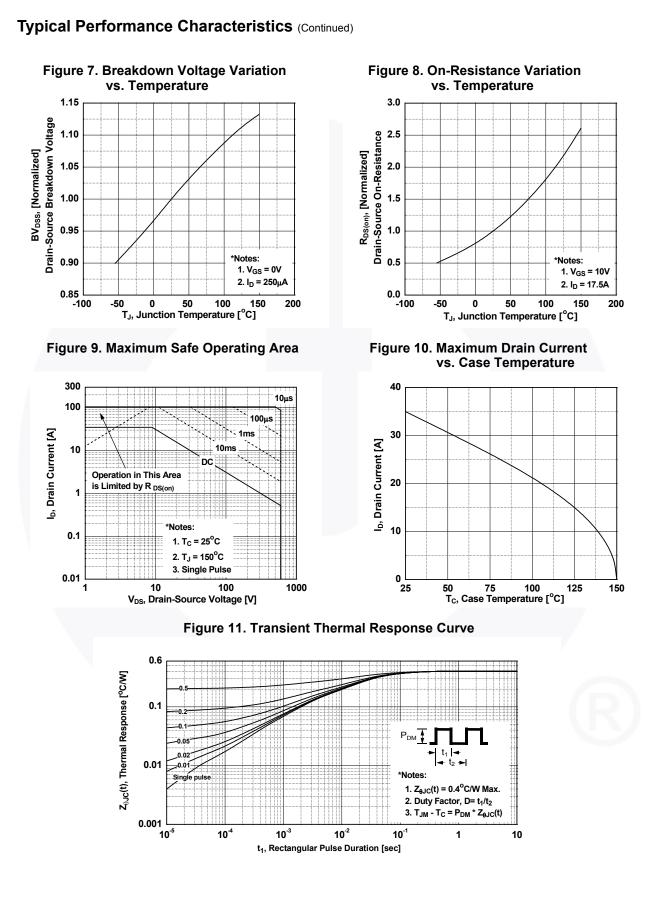
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FCA35N60 Rev. C2

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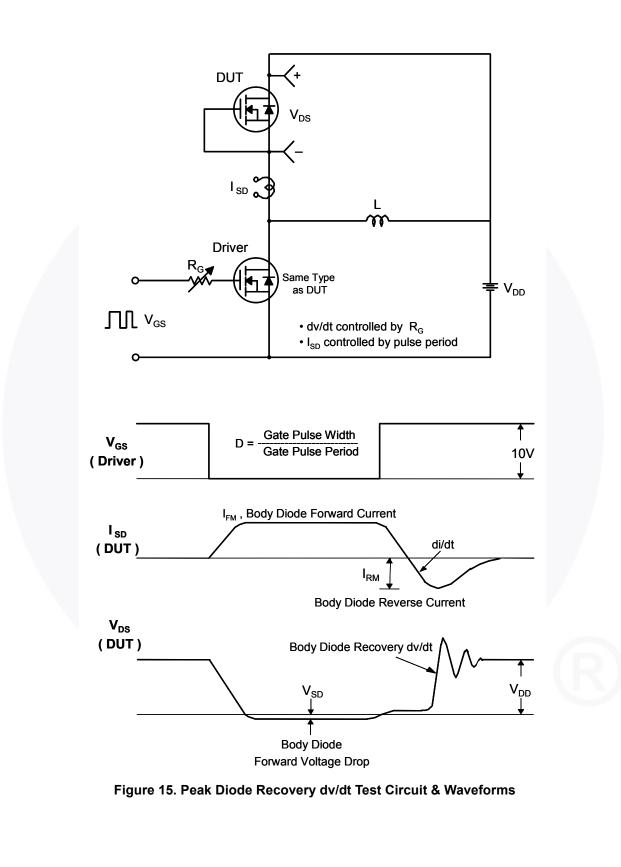


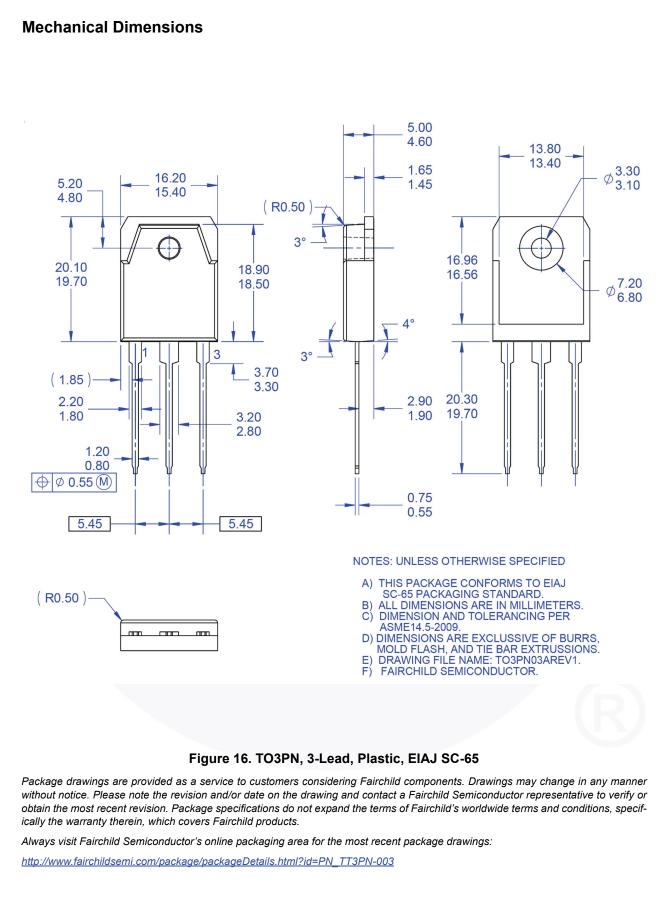
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 V_{GS} ξ ק Q_g V_{DS} Q_{gd} Q_{gs} •1 DUT I_G = const. Charge Figure 12. Gate Charge Test Circuit & Waveform R VDS V_{DS} 90% ο V_{DD} GS R_{G} 10% V_{GS} DUT V_{GS} ∏ 0 Figure 13. Resistive Switching Test Circuit & Waveforms L $E_{AS} = \frac{1}{2} L I_{AS}^2$ V_{DS} $\mathsf{BV}_{\mathsf{DSS}}$ ID o AS R_G **∔** ∨_{DD} $I_D(t)$ V_{GS} $V_{DS}(t)$ V_{DD} DUT Time t_p Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

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